

VERTICAL WAFER COMPACT FLIP CHIP FEEDER

ABSTRACT

A vertical wafer compact flip chip feeder device includes a loading station for providing a loading location where a flip chip wafer having first and second planar surfaces is received such that the first and second planar surfaces are substantially perpendicular to a first plane. The flip chip feeder device further includes a pick-up station for providing a pick-up location where individual flip chips are retrieved from the flip chip wafer. A wafer translating assembly translates the flip chip wafer between the loading and pick-up stations with the first and second planar surfaces of the flip chip wafer remaining substantially perpendicular to the first plane. A chip pick-up assembly retrieves the individual flip chips from the flip chip wafer at the pick-up station and flips the individual flip chips to a flipped position such that first and second planar surfaces of the individual flip chips are substantially parallel with the first plane.

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